## **Fiber Optic Receiver**

## OPF2412, OPF2412T



#### Features:

- Up to 5Mbps operation
- 850nm wavelength
- ST<sup>®</sup> style port
- CMOS and TTL compatible
- Wave solderable
- Wide temperature range

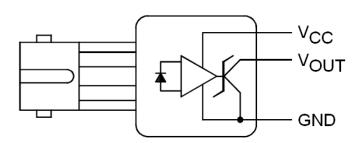


#### **Description:**

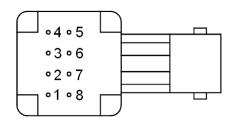
The OPF2412 family is a low cost digital output fiber optic receiver. The lensed optical system keeps the receiver response consistent for all fiber sizes which makes it idea for use on fibers as small as  $50/125 \mu m$ . The design incorporates a monolithic photo-IC comprised of a photodetector and DC amplifier driving an open collector output Schottky transistor. The output makes the OPF2412 compatible with TTL and CMOS logic. The receiver is designed to operate from a single +5 V supply. A bypass capacitor (0.1 µF ceramic) should be connected from  $V_{CC}$  to GND of the receiver.

### **Applications:**

- Industrial Ethernet equipment
- Copper-to-fiber media conversion
- Intra-system fiber optic links
- Video surveillance systems



"T" suffix = Threaded ST<sup>®</sup> package



PIN	FUNCTION			
1	Not Connected			
2	V <sub>cc</sub>			
3	GND			
4	Not Connected			
5	Not Connected			
6	V <sub>out</sub>			
7	GND			
8	Not Connected			





 $\mathsf{ST}^{\mathbb{R}}$  is a registered trademark of AT&T.

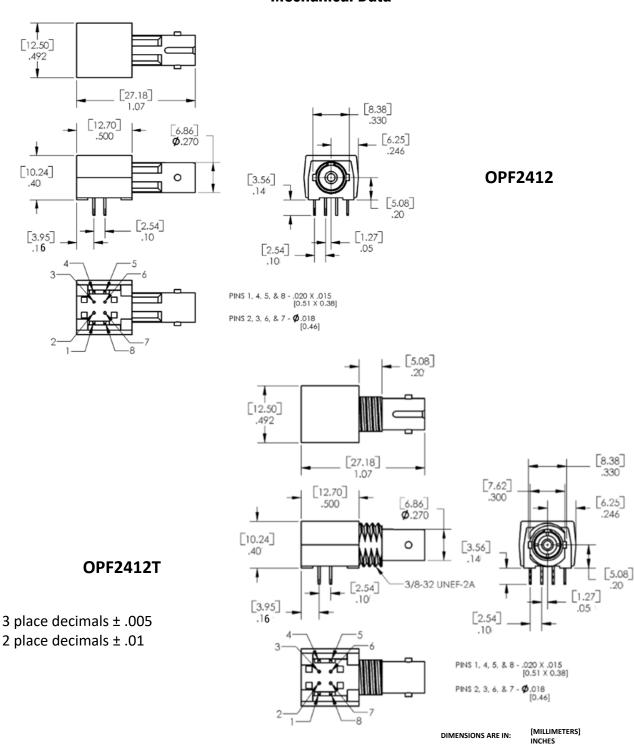
Pins 3 & 7 are electrically connected to the header. Pins 1,4,5 & 8 are mechanically connected together.

# **Fiber Optic Receiver**

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### **Mechanical Data**



# **Fiber Optic Receiver**

OPF2412, OPF2412T



## **Electrical Specifications**

### **Absolute Maximum Ratings** (T<sub>A</sub> = 25° C unless otherwise noted)

Storage Temperature Range	-55° C to +85° C
Operating Temperature Range	-40° C to +85° C
Lead Soldering Temperature <sup>(1)</sup>	260° C
Supply Voltage	-0.5 V to 7.0 V
Output Current	25 mA
Output Voltage	-0.5 V to 18.0 V
Open Collector Power Dissipation	40 mW
Fan Out (TTL)	5 <sup>(2)</sup>

### **Electrical Characteristics** (T<sub>A</sub> = 25° C unless otherwise noted)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS	TEST CONDITIONS
I <sub>OH</sub>	High Level Output Current		5	250	μΑ	V <sub>O</sub> = 18 V, P <sub>R</sub> < -40 dBm
V <sub>OL</sub>	Low Level Output Voltage		0.4	0.5	V	I <sub>O</sub> = 8 mA, P <sub>R</sub> > -24 dBm
I <sub>CCH</sub>	High Level Supply Current		3.5	6.3	mA	V <sub>CC</sub> = 5.25 V, P <sub>R</sub> < -40 dBm
I <sub>CCL</sub>	Low Level Supply Current		6.2	10	mA	V <sub>CC</sub> = 5.25 V, P <sub>R</sub> > -24 dBm
$P_RH$	Peak Input Power Level, Logic HIGH			0.1	μW	I <sub>p</sub> = 850 nm
$P_RL$	Peak Input Power Level, Logic LOW	2.9		120	μW	I <sub>p</sub> = 850 nm, I <sub>OL</sub> = 8 mA
$P_RL$	Peak Input Power Level, Logic LOW	4.0		100	μW	-40 °C £ T <sub>A</sub> £ +85 °C
t <sub>PLHR</sub>	Propagation Delay LOW to HIGH		65		ns	P <sub>R</sub> = -21 dBm, Data Rate = 5 MBd
t <sub>PHLR</sub>	Propagation Delay HIGH to LOW		49		ns	P <sub>R</sub> = -21 dBm, Data Rate = 5 MBd

#### Notes:

1. Maximum of 5 seconds with soldering iron. Duration can be extended to 10 seconds when flow soldering. RMA flux is recommended.

2. 8 mA load (5 x 1.6 mA),  $R_L = 560$  W.

2 6 560 2 74LS00

### **Application Circuit**